

# YIBO LIN

PhD student ◊ Department of Electrical & Computer Engineering  
University of Texas at Austin, Austin, TX 78712 ◊ University of Texas at Austin  
1600 Wickersham Lane apt 3089, Austin, TX 78741, USA ◊ Phone: +1 512-605-7126  
yibolin@utexas.edu ◊ [www.cerc.utexas.edu/~yibolin](http://www.cerc.utexas.edu/~yibolin)

## RESEARCH INTERESTS

---

Nanometer IC design for manufacturability, modeling and optimization in VLSI CAD

## EDUCATION

---

<b>University of Texas at Austin, TX, USA</b> Ph.D. student, Department of Electrical and Computer Engineering Advisor: David Z. Pan (GPA 3.96/4.0)	<i>Aug. 2013 – Present</i>
<b>Shanghai Jiao Tong University, Shanghai, P.R.China</b> B.S., Department of Microelectronics (GPA 91.17/100) (Rank top 1/60)	<i>Sep. 2009 – Jun. 2013</i>

## EXPERIENCE

---

<b>IMEC, Leuven, Belgium</b> Internship Design technology co-optimization for emerging lithography options	<i>Sep. 2016 – Nov. 2016</i>
<b>Chinese University of Hong Kong, China</b> Summer Intern Quantum computing	<i>Jun. 2016 – Aug. 2016</i>
<b>Cadence Design System, TX, USA</b> Summer Intern Routability driven detailed placement	<i>May 2015 – Aug. 2015</i>
<b>Oracle Inc., TX, USA</b> Summer Intern Incremental timing driven detailed placement	<i>May 2014 – Aug. 2014</i>
<b>ECE Department, University of Texas at Austin, TX, USA</b> Graduate Research Assistant Multiple patterning lithography layout decomposition Stitch aware detailed placement Triple-patterning aware detailed placement Dummy fill insertion Detailed-routing-driven placement	<i>Jan. 2014 – Present</i>

## PUBLICATIONS

---

### Journal Papers

- [J2] Yu, Bei and Xu, Xiaoqing and Roy, Subhendu and **Lin, Yibo** and Ou, Jiaojiao and Pan, David Z., “Design for manufacturability and reliability in extreme-scaling VLSI”, Science China Information Sciences, 2016. (**Invited paper**)
- [J1] Yu, Bei and Xu, Xiaoqing and Gao, Jih-Rong and **Lin, Yibo** and Li, Zhuo and Alpert, Charles and Pan, David Z., “Methodology for standard cell compliance and detailed placement for triple patterning lithography”, IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD), May, 2015.

### Conference Papers

- [C9] Ou, Jiaojiao and Yu, Bei and Xu, Xiaoqing and Mitra, Joydeep and **Lin, Yibo** and Pan, David Z., “DSAR: DSA aware routing with simultaneous DSA guiding pattern and double patterning assignment”, ACM International Symposium on Physical Design (ISPD), Portland, OR, Mar 19-22, 2017.
- [C8] **Lin, Yibo** and Yu, Bei and Xu, Xiaoqing and Gao, Jih-Rong and Viswanathan, Natarajan and Liu, Wen-Hao and Li, Zhuo and Alpert, Charles J and Pan, David Z., “MrDP: Multiple-row detailed placement of heterogeneous-sized cells for advanced nodes”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 7-10, 2016.
- [C7] Tao, Yudong and Yan, Changhao and **Lin, Yibo** and Wang, Sheng-Guo and Pan, David Z. and Zeng, Xuan, “A novel unified dummy fill insertion framework with SQP-based optimization method”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 7-10, 2016.
- [C6] **Lin, Yibo** and Yu, Bei and Pan, David Z., “Detailed placement in advanced technology nodes: a survey”, IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT), Hangzhou, China, Oct 25-28, 2016. (**Invited paper**)
- [C5] **Lin, Yibo** and Xu, Xiaoqing and Yu, Bei and Baldick, Ross and Pan, David Z., “Triple/quadruple patterning layout decomposition via novel linear programming and iterative rounding”, Proceedings of SPIE, San Jose, CA, Feb 21-25, 2016. (**Best Student Paper Award**)
- [C4] **Lin, Yibo** and Yu, Bei and Zou, Yi and Li, Zhuo and Alpert, Charles J and Pan, David Z., “Stitch aware detailed placement for multiple e-beam lithography”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), Macau, China, Jan 25-28, 2016.
- [C3] **Lin, Yibo** and Yu, Bei and Xu, Biying and Pan, David Z., “Triple patterning aware detailed placement toward zero cross-row middle-of-line conflict”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 2-6, 2015.
- [C2] **Lin, Yibo** and Yu, Bei and Pan, David Z., “High performance dummy fill insertion with coupling and uniformity constraints”, ACM/IEEE Design Automation Conference (DAC), San Francisco, CA, Jun 7-11, 2015.
- [C1] Pan, David Z. and Liebmann, Lars and Yu, Bei and Xu, Xiaoqing and **Lin, Yibo**, “Pushing multiple patterning in sub-10nm: are we ready?”, ACM/IEEE Design Automation Conference (DAC), San Francisco, CA, Jun 7-11, 2015. (**Invited Paper**)

## RELATED COURSES

---

• EE382M: VLSI I	<i>Prof. Michael Orshansky</i>
• EE382N: Computer Architecture	<i>Prof. Aater Suleman</i>
• EE382V: Optimization Issues in VLSI CAD	<i>Prof. David Pan</i>
• EE382M: VLSI II	<i>Prof. Jacob Abraham</i>
• EE380L: Engineer Programming Languages	<i>Prof. Craig Chase</i>
• EE382V: Nanometer Scale IC Design	<i>Prof. Michael Orshansky</i>
• EE382V: VLSI Physical Design Automation	<i>Prof. David Pan</i>
• EE381V: Advanced Algorithms	<i>Prof. Evdokia Nikolova</i>
• EE382V: Advanced Programming Tools	<i>Prof. Aziz Adnan</i>
• EE380N: Optimization in Engineering Systems	<i>Prof. Ross Baldick</i>
• CS383C: Numerical Analysis: Linear Algebra	<i>Prof. Robert van de Geijn</i>

## SKILLS

---

### Programming Languages

C/C++, Python, Verilog

### Web Development

HTML5, JavaScript/jQuery

## EDA Tools

Cadence Virtuoso, Synopsys Design Compiler, Synopsys IC Compiler

## AWARDS AND HONORS

---

Franco Cerrina Memorial Best Student Paper Award	SPIE	2016
A. Richard Newton Young Student Fellow	DAC	2014
National Scholarship	Shanghai Jiao Tong University	2012
Samsung Scholarship	Shanghai Jiao Tong University	2011
The Second Prize Scholarship	Shanghai Jiao Tong University	2010